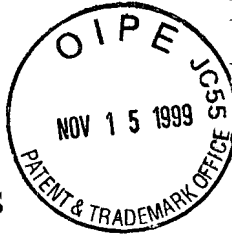


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Mostafazadeh, Shahram; Smith, Joseph O.  
Assignee: National Semiconductor Corporation  
Title: LEAD FRAME DESIGN FOR INCREASED CHIP PINOUT  
Serial No.: 09/054,380 Filed: April 2, 1998  
Batch No.: C12 Date Allowed: September 27, 1999  
Examiner: H. Duong Group Art Unit: 2823  
Docket No.: NS-3856 US



San Jose, California

## BOX ISSUE FEES

Attn: Official Draftsperson

ASSISTANT COMMISSIONER FOR PATENTS

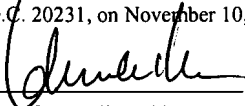
Washington, D. C. 20231

**SUBMISSION OF FORMAL DRAWINGS**


Dear Sir:

Applicants submit four (4) sheets of formal drawings, consisting of Figures 1a-1, 1a-2, 1b-1, 1b-2, 1c-1, 1c-2, 2a-1, 2a-2, 2b-1, 2b-2, 2c-1, 2c-2, 2d-1 and 2d-2, in the above-named application. If there are any questions regarding these drawings, please call the undersigned at (408) 453-9200.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on November 10, 1999.

  
Attorney for Applicant(s)11/10/99  
Date of Signature

Respectfully submitted,



Edward C. Kwok  
Attorney for Applicants  
Reg. No. 33,938